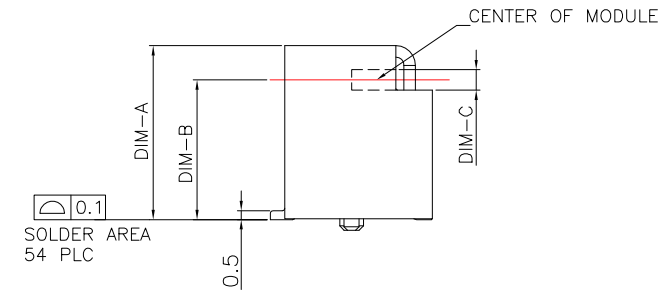
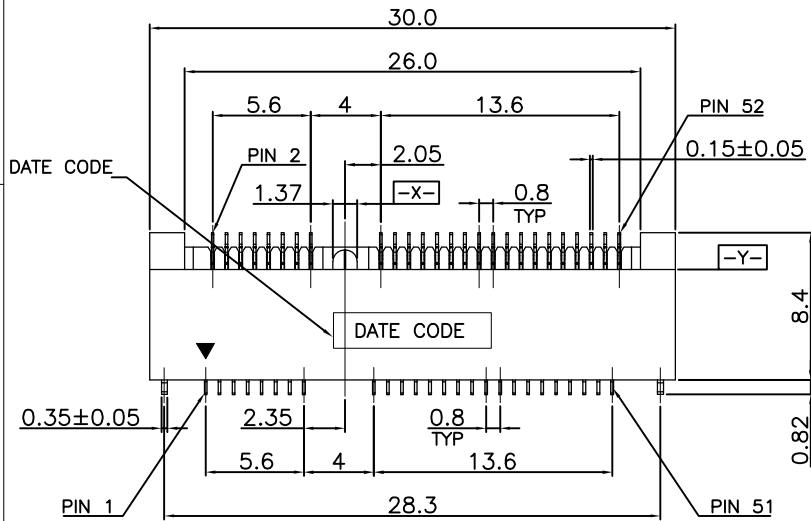




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SPECIFICATION:

1. ELECTRICAL

- 1.1 Current Rating: 0.5A per pin
- 1.2 Voltage Rating: 50V DC
- 1.3 Contact Resistance: 5 mΩ Max
- 1.4 Insulation Resistance: 500MΩ Min
- 1.5 Dielectric Withstanding Voltage: 300VAC

2. MECHANICAL

- 2.1 Durability: 100 Cycle
- 2.2 Insertion Force: 2.3Kgf max.
- 2.3 Extraction Force: 2.3Kgf max.

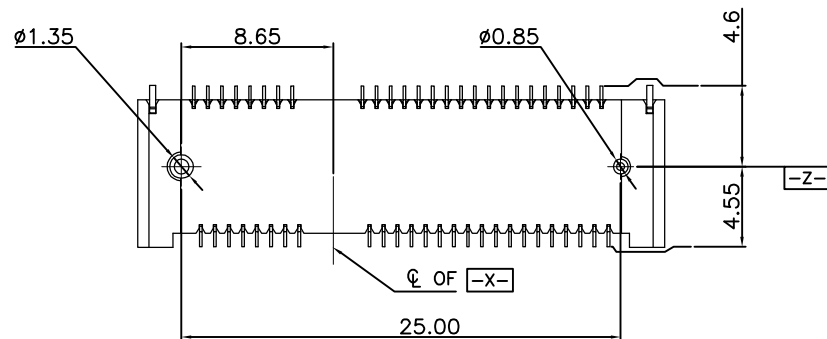
3. ENVIRONMENTAL

- 3.1 Operating temperature range: -40 °C ~ +85 °C
- 3.2 Storage temperature range: -40 °C ~ +85 °C

4. SOLDER ABILITY

- 4.1 Recommended IR Reflow Temperature: 260 °C 10Sec

LTEM NO	DIM-A	DIM-B	DIM-C
	4.0mm	2.05mm	1.12mm
	5.2mm	3.25mm	1.12mm
	5.6mm	3.65mm	1.12mm
	7.0mm	5.05mm	1.12mm
	8.0mm	6.05mm	1.16mm
	9.0mm	7.05mm	1.16mm
	9.9mm	7.95mm	1.16mm

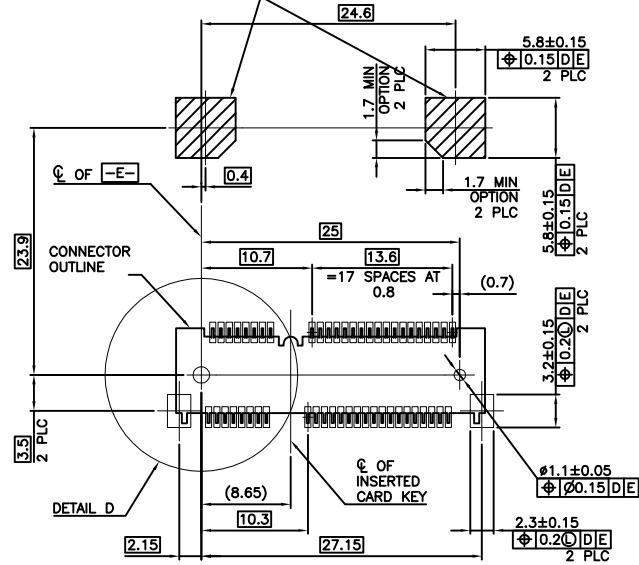


UNLESS OTHERWISE SPECIFIED TOLERANCES		Bossie (博锡)			
DECIMALS:	ANGLES:	TITLE	mPCI-E 0.8mm P数:52		
X :±0.35	X :±2°	DWN	PART NO.	BX-JSZ0.8-5.6H52P	
X.X :±0.25	X.X :±1°	CHKD	SCALE:1:1	UNIT: mm	REV: A4
X.XX :±0.15		APVD	SIZE: A4	SHEET:1OF 1	
CUSTOMER COPY					

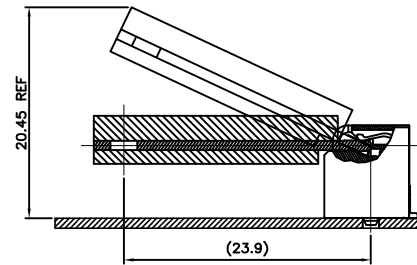
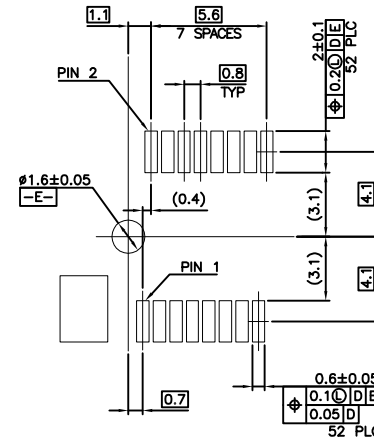


REV.	ECN NO OR DESCRIPTION	REVISED	DATE

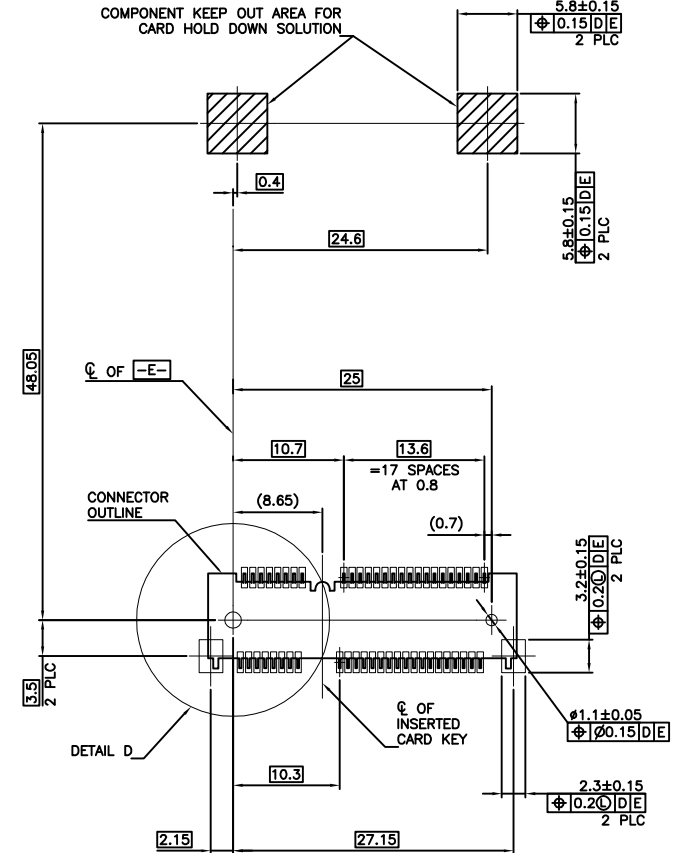
COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



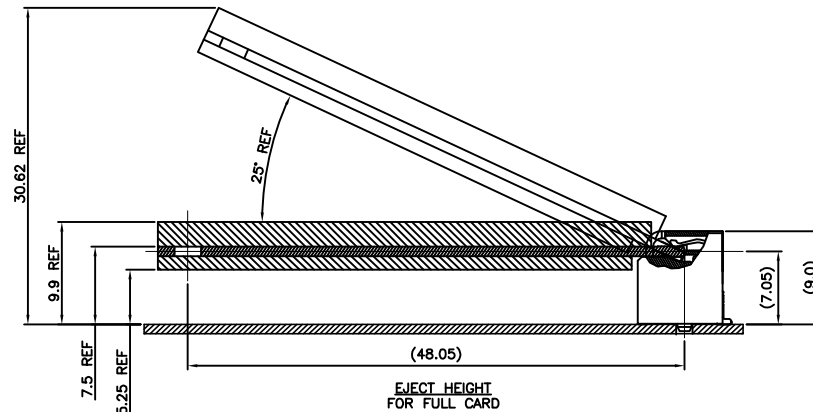
-D- IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)



COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



-D- IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR FULL CARD CONNECTOR
(TOP VIEW)



UNLESS OTHERWISE
SPECIFIED TOLERANCES

DECIMALS: ANGLES:
X :±0.35 X :±2°
X.X :±0.25 X.X :±1°
X.XX :±0.15

Bossie (博锡)

TITLE	mPCI-E 0.8mm P数:52		
DWN	PART NO.	BX-JS20.8-5.6H52P	
CHKD	SCALE:1:1	UNIT: mm	
APVD	SIZE: A4	SHEET:1OF 1	REV: A4

CUSTOMER COPY